

## N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY			
$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A) <sup>a, e</sup>	$Q_g$ (Typ.)
40	0.0098 at $V_{GS} = 10$ V	35	37 nC
	0.011 at $V_{GS} = 4.5$ V	30	

### FEATURES

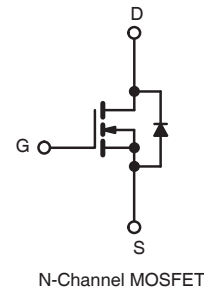
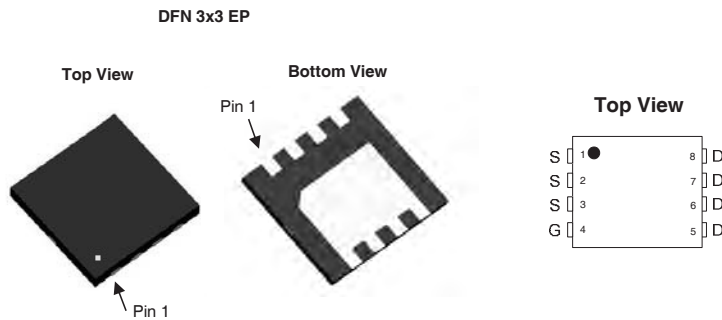
- DT-Trench Power MOSFET
- 100 %  $R_g$  and UIS Tested

### APPLICATIONS

- Notebook PC Core
- VRM/POL



RoHS  
COMPLIANT



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C, unless otherwise noted)			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current ( $T_J = 175$ °C)	$I_D$	$T_C = 25$ °C	35 <sup>a, e</sup>
		$T_C = 70$ °C	30 <sup>e</sup>
		$T_A = 25$ °C	14 <sup>b, c</sup>
		$T_A = 70$ °C	12 <sup>b, c</sup>
Pulsed Drain Current	$I_{DM}$	140	mJ
Avalanche Current Pulse	$I_{AS}$	25	
Single Pulse Avalanche Energy	$E_{AS}$	52	
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25$ °C	35 <sup>a, e</sup>
		$T_A = 25$ °C	18 <sup>b, c</sup>
Maximum Power Dissipation	$P_D$	$T_C = 25$ °C	30
		$T_C = 70$ °C	20
		$T_A = 25$ °C	3.2 <sup>b, c</sup>
		$T_A = 70$ °C	2 <sup>b, c</sup>
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to 175	°C

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b, d</sup>	$R_{thJA}$	35	49	°C/W
Maximum Junction-to-Case	$R_{thJC}$	4	5	

Notes:

- Based on  $T_C = 25$  °C.
- Surface mounted on 1" x 1" FR4 board.
- $t = 10$  s.
- Maximum under steady state conditions is 90 °C/W.
- Calculated based on maximum junction temperature. Package limitation current is 10 A.

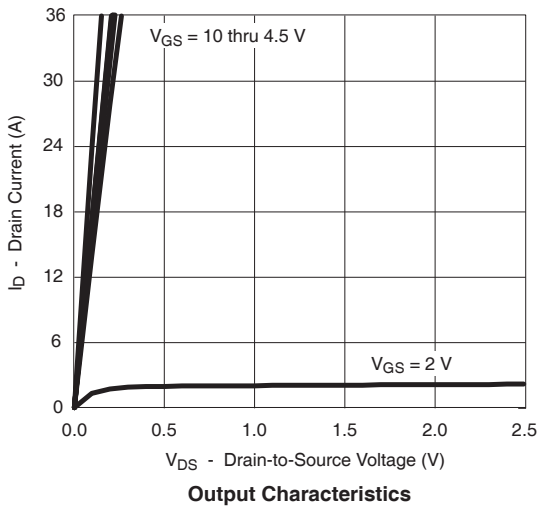
<b>SPECIFICATIONS</b> ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min .	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	40			V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		35		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 5.5		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1		3	V
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 32\text{ V}, V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 32\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$			10	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	35			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 10\text{ A}$		0.0098	0.011	$\Omega$
		$V_{GS} = 4.5\text{ V}, I_D = 8\text{ A}$		0.011	0.013	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 32\text{ V}, I_D = 10\text{ A}$		90		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 32\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		1680		$\mu\text{F}$
Output Capacitance	$C_{oss}$			910		
Reverse Transfer Capacitance	$C_{rss}$			301		
Total Gate Charge	$Q_g$	$V_{DS} = 32\text{ V}, V_{GS} = 10\text{ V}, I_D = 10\text{ A}$		37		nC
		$V_{DS} = 32\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 8\text{ A}$		25		
$Q_{gs}$			17			
$Q_{gd}$			8			
Gate Resistance	$R_g$	$f = 1\text{ MHz}$		1.5	2.3	$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 32\text{ V}, R_L = 0.555\text{ }\Omega$ $I_D \cong 10\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$		15	20	ns
Rise Time	$t_r$			10	17	
Turn-Off Delay Time	$t_{d(off)}$			30	45	
Fall Time	$t_f$			8	15	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 32\text{ V}, R_L = 0.625\text{ }\Omega$ $I_D \cong 8\text{ A}, V_{GEN} = 4.5\text{ V}, R_g = 1\text{ }\Omega$		35	53	
Rise Time	$t_r$			60	70	
Turn-Off Delay Time	$t_{d(off)}$			25	43	
Fall Time	$t_f$			8	12	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$			35	A
Pulse Diode Forward Current <sup>a</sup>	$I_{SM}$				140	
Body Diode Voltage	$V_{SD}$	$I_S = 12\text{ A}$		0.8	1.2	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$		50	72	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			65	96	nC
Reverse Recovery Fall Time	$t_a$			23		ns
Reverse Recovery Rise Time	$t_b$			20		

Notes:

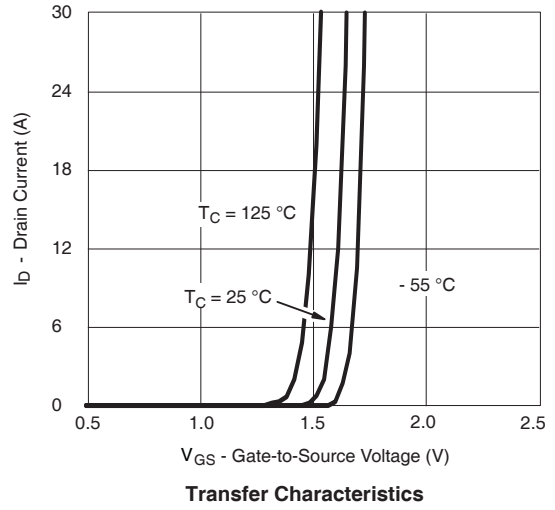
- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

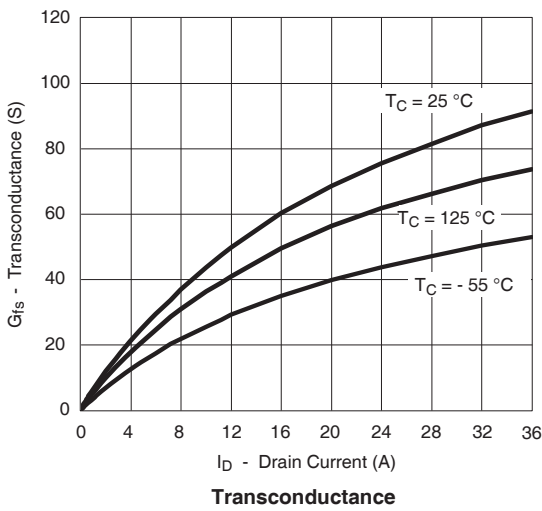
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



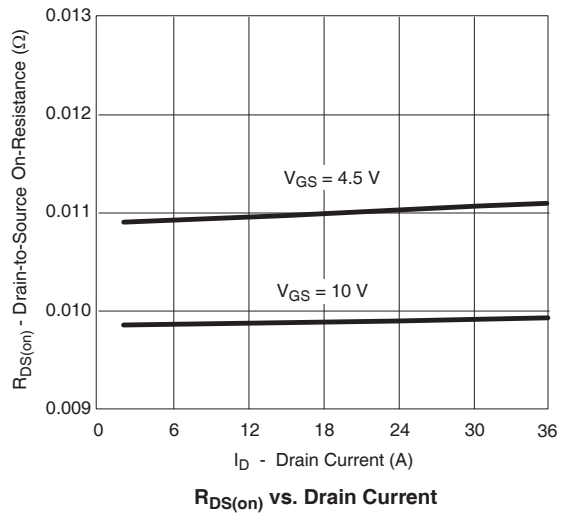
**Output Characteristics**



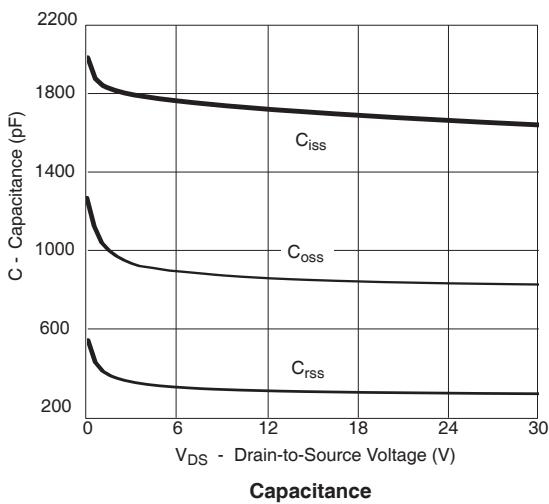
**Transfer Characteristics**



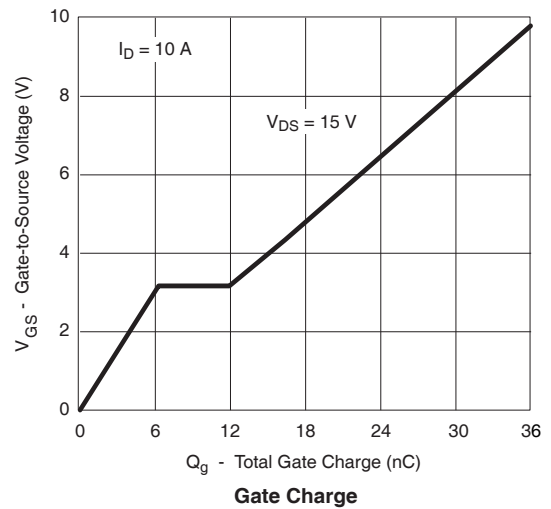
**Transconductance**



**$R_{DS(on)}$  vs. Drain Current**

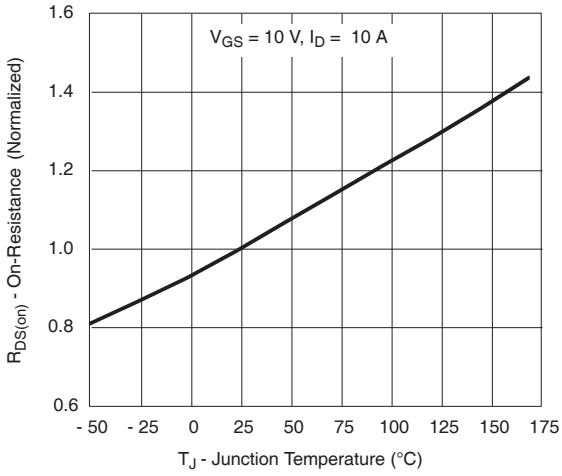


**Capacitance**

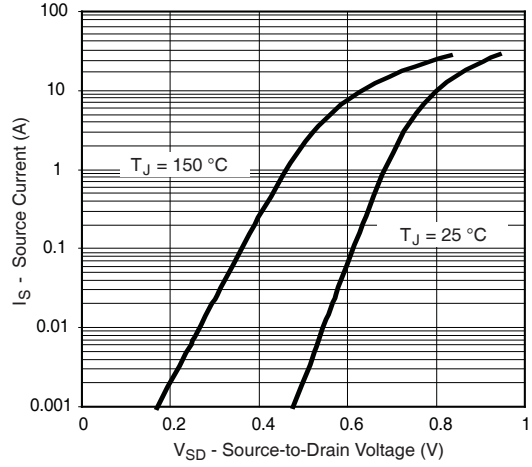


**Gate Charge**

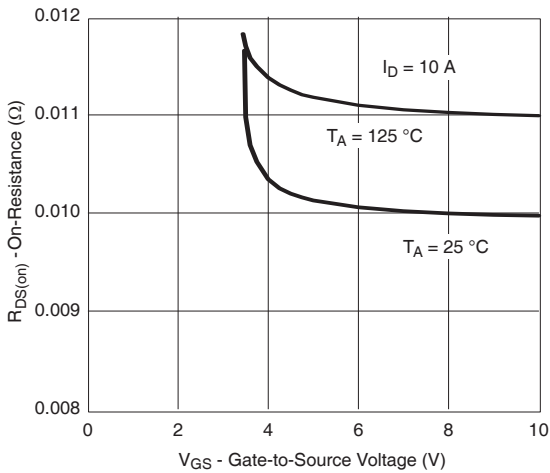
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



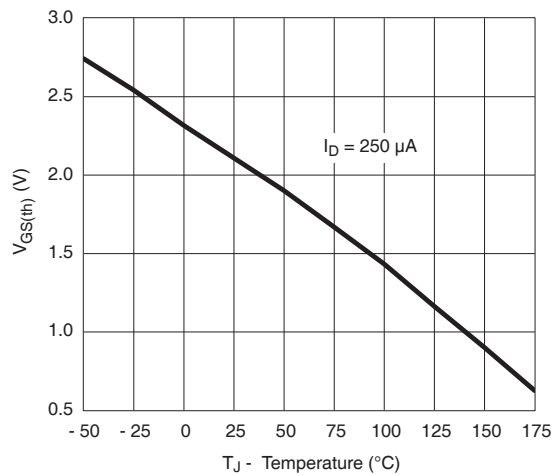
**On-Resistance vs. Junction Temperature**



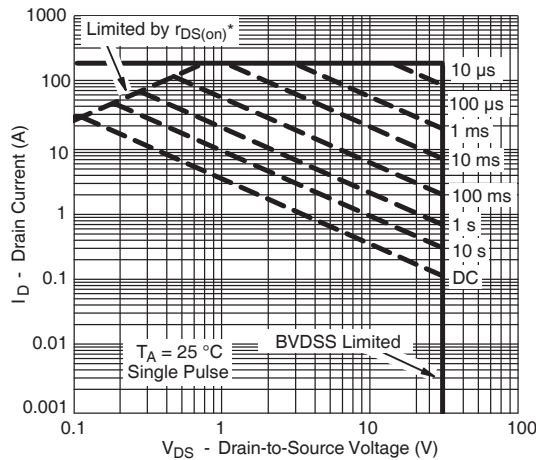
**Forward Diode Voltage vs. Temperature**



**$R_{DS(on)}$  vs.  $V_{GS}$  vs. Temperature**



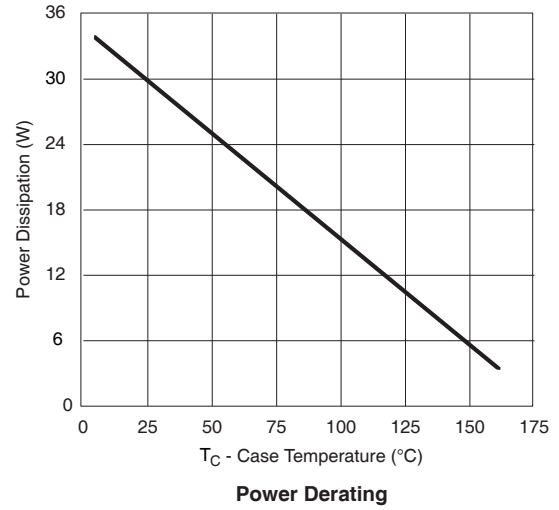
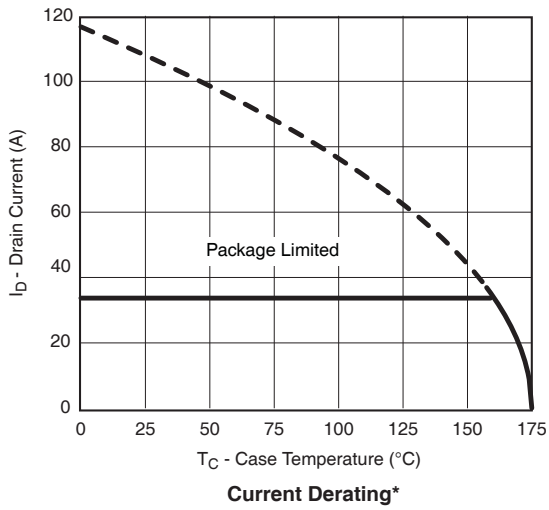
**Threshold Voltage**



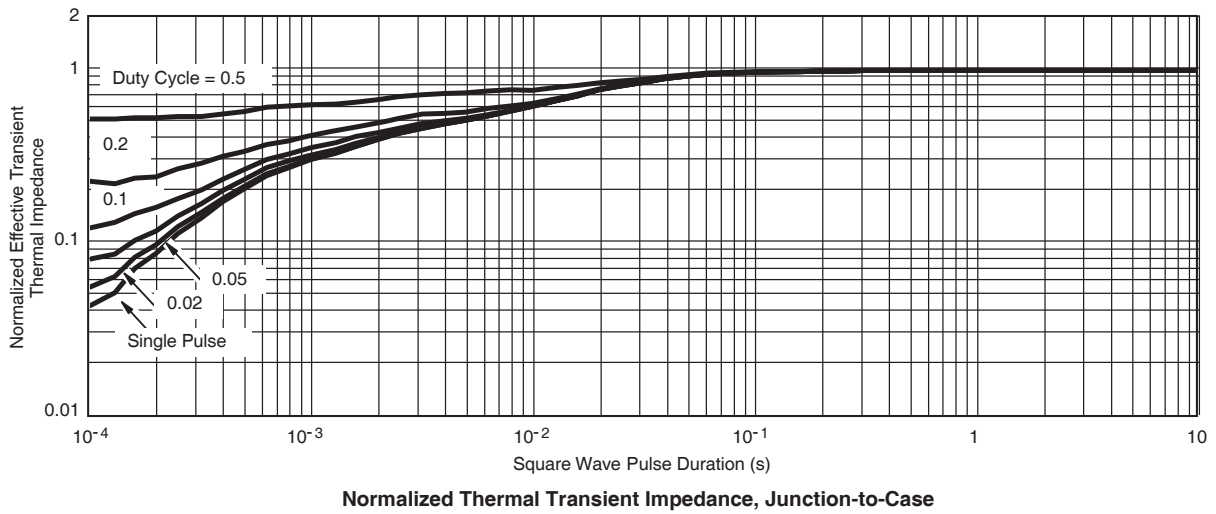
**Safe Operating Area, Junction-to-Ambient**

\* $V_{GS} >$  minimum  $V_{GS}$  at which  $r_{DS(on)}$  is specified

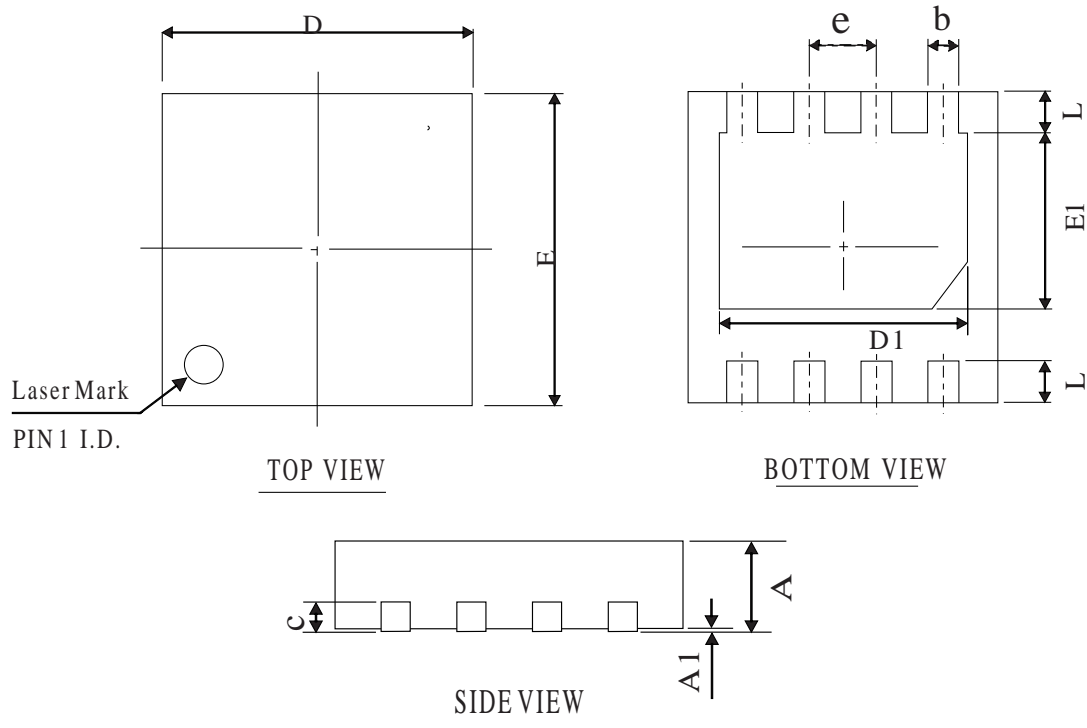
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 175\text{ °C}$ , using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



## DFN3\*3-8L PACKAGE OUTLINE



### COMMON DIMENSIONS (UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
<b>A</b>	0.60	0.75	0.90
<b>A1</b>	0.00	0.02	0.08
<b>b</b>	0.20	0.30	0.45
<b>D</b>	2.85	3.00	3.15
<b>E</b>	2.85	3.00	3.15
<b>D1</b>	2.10	2.40	2.70
<b>E1</b>	1.50	1.70	2.00
<b>L</b>	0.20	0.40	0.60
<b>c</b>	0.203 REF		
<b>e</b>	0.65 BSC		

### OTHER DIMENSIONS

<b>A</b>	0.50	0.55	0.60
<b>A</b>	0.40	0.45	0.50

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